

6-pack-integrated intelligent power system

Power section

SKiiP 613GD061-3DUL

Preliminary Data

Features

- SKiiP technology inside
- Low loss IGBTs
- CAL diode technology
- Integrated current sensor
- Integrated temperature sensor
- Integrated heat sink
- IEC 60721-3-3 (humidity) class 3K3/IE32 (SKiiP® 3 System)
- IEC 68T.1 (climate) 40/125/56 (SKiiP® 3 power section)
- UL recognized file no. E 63 532 (SKiiP® 3 power section)

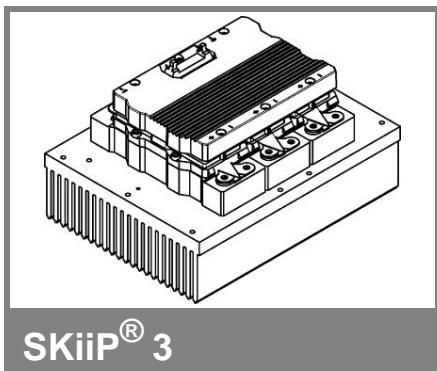
1) with assembly of suitable MKP capacitor per terminal (SEMIKRON type is recommended)

Absolute Maximum Ratings		$T_s = 25^\circ\text{C}$, unless otherwise specified		
Symbol	Conditions	Values		Units
IGBT				
V_{CES}		600		V
$V_{CC}^{1)}$	Operating DC link voltage	400		V
V_{GES}		± 20		V
I_C	$T_s = 25 \text{ (70)}^\circ\text{C}$	600 (450)		A
Inverse diode				
$I_F = -I_C$	$T_s = 25 \text{ (70)}^\circ\text{C}$	560 (420)		A
I_{FSM}	$T_j = 150^\circ\text{C}$, $t_p = 10 \text{ ms}$; sin	6000		A
I^2t (Diode)	Diode, $T_j = 150^\circ\text{C}$, 10 ms	180		kA ² s
T_j (T_{stg})		- 40 ... + 150 (125)		°C
V_{isol}	rms, AC, 1 min	2500		V
$I_{AC\text{-terminal}}$	per AC terminal, rms, $T_s = 70^\circ\text{C}$,	400		A
	$T_{\text{terminal}} < 115^\circ\text{C}$			

Characteristics		$T_s = 25^\circ\text{C}$, unless otherwise specified		
Symbol	Conditions	min.	typ.	max.
IGBT				
V_{CEsat}	$I_C = 300 \text{ A}$, $T_j = 25 \text{ (125)}^\circ\text{C}$; measured at terminal	1,5 (1,6)	1,8	V
V_{CEO}	$T_j = 25 \text{ (125)}^\circ\text{C}$; at terminal	0,8 (0,7)	1 (0,9)	V
r_{CE}	$T_j = 25 \text{ (125)}^\circ\text{C}$; at terminal	2,4 (3,1)	2,7 (3,4)	mΩ
I_{CES}	$V_{GE} = 0 \text{ V}$, $V_{CE} = V_{CES}$, $T_j = 25 \text{ (125)}^\circ\text{C}$	1,2 (36)		mA
$E_{on} + E_{off}$	$I_C = 300 \text{ A}$, $V_{CC} = 300 \text{ V}$	27		mJ
	$T_j = 125^\circ\text{C}$, $V_{CC} = 400 \text{ V}$	39		mJ
$R_{CC+EE'}$	terminal chip, $T_j = 25^\circ\text{C}$	0,5		mΩ
L_{CE}	top, bottom	12		nH
C_{CHC}	per phase, AC-side	1,7		nF
Inverse diode				
$V_F = V_{EC}$	$I_F = 300 \text{ A}$, $T_j = 25 \text{ (125)}^\circ\text{C}$ measured at terminal	1,3 (1,2)	1,5	V
V_{TO}	$T_j = 25 \text{ (125)}^\circ\text{C}$	0,8 (0,6)	1 (0,8)	V
r_T	$T_j = 25 \text{ (125)}^\circ\text{C}$	1,5 (1,9)	1,7 (2)	mΩ
E_{rr}	$I_C = 300 \text{ A}$, $V_{CC} = 300 \text{ V}$	5		mJ
	$T_j = 125^\circ\text{C}$, $V_{CC} = 400 \text{ V}$	6		mJ
Mechanical data				
M_{dc}	DC terminals, SI Units	6	8	Nm
M_{ac}	AC terminals, SI Units	13	15	Nm
w	SKiiP® 3 System w/o heat sink	2,4		kg
w	heat sink	7,5		kg

Thermal characteristics (PX16 heat sink with fan SKF16B-230-1); "s" reference to heat sink; "r" reference to built-in temperature sensor (acc.IEC 60747-15)							
$R_{th(j-s)I}$	per IGBT			per diode			K/W
$R_{th(j-s)D}$							K/W
Z_{th}	R_i (mK/W) (max. values)			$\tau_{ai}(s)$			
	1	2	3	4	1	2	3
$Z_{th(j-r)I}$	10,2	28,8	21	0	363	0,18	0,04
$Z_{th(j-r)D}$	36	36	54	60	30	5	0,25
$Z_{th(r-a)}$	2,1	20	5,5	1,4	210	85	11
							0,4

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6-pack-integrated intelligent power system

**6-pack
integrated gate driver
SKiiP 613GD061-3DUL**

Preliminary Data

Gate driver features

- CMOS compatible inputs
- Wide range power supply
- Integrated circuitry to sense phase current, heat sink temperature and DC-bus voltage (option)
- Short circuit protection
- Over current protection
- Over voltage protection (option)
- Power supply protected against under voltage
- Interlock of top/bottom switch
- Isolation by transformers
- Fibre optic interface (option for GB-types only)
- IEC 68T.1 (climate) 40/85/56 (SKiiP® 3 gate driver)

Absolute Maximum Ratings		Values	Units
Symbol	Conditions		
V_{S2}	unstabilized 24 V power supply	30	V
V_i	input signal voltage (high)	15 + 0,3	V
dv/dt	secondary to primary side	75	kV/μs
V_{isolIO}	input / output (AC, rms, 2 s)	2500	V
V_{isolPD}	partial discharge extinction voltage, rms, $Q_{PD} \leq 10$ pC;	960	V
V_{isol12}	output 1 / output 2 (AC, rms, 2 s)	1500	V
f	switching frequency	20	kHz
$T_{op} (T_{stg})$	operating / storage temperature	- 40 ... + 85	°C

Characteristics		$(T_a = 25^\circ C)$		
Symbol	Conditions	min.	typ.	max.
V_{S2}	supply voltage non stabilized	13	24	27
I_{S2}	$V_{S2} = 24$ V	$375+30*f/kHz+0,00111*(I_{AC}/A)^2$		
V_{iT+}	input threshold voltage (High)	11,2		V
V_{iT-}	input threshold voltage (Low)		5,4	V
R_{IN}	input resistance	10		kΩ
C_{IN}	input capacitance	1		nF
$t_{d(on)IO}$	input-output turn-on propagation time	1,1		μs
$t_{d(off)IO}$	input-output turn-off propagation time	1,1		μs
$t_{pERRRESET}$	error memory reset time	9		μs
t_{TD}	top / bottom switch interlock time	3,3		μs
$I_{analogOUT}$	max. 5 mA; 8 V corresponds to 15 V supply voltage for external components	600		A
I_{s1out}	max. load current		50	mA
I_{TRIPSC}	over current trip level ($I_{analog OUT} = 10$ V)		750	A
T_{tp}	over temperature protection	110		°C
U_{DCTRIP}	U_{DC} -protection ($U_{analog OUT} = 9$ V); (option for GB type)		400	V

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